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MINISTRY OF ECONOMIC AFFAIRS
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Certificate

The Patent entitled : **DIE PACKAGE STRUCTURE**

has been granted according to the Patent Law of the Republic of China.

The followings are the relevant references:

Patentee(s) : **CHENMKO ENTERPRISE CO., LTD.**

Inventor(s) : **LIAO, HUANG-SHUN**

Patent Number : **Invention No. I867410**

Term of Patent : **From Dec. 21, 2024 to Jan. 15, 2043**

This certificate is only for general reference, when legal matter is involved,
the original Chinese document shall be referred.

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Director General

Date: Jan. 13, 2025